

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A computing system comprising:
a circuit board;
a first connector portion electrically connected to the circuit board;
an electronic component including:
a first electronic device;
a second connector portion electrically coupled to the electronic device
and connected to the first connector portion along an axis; and
a plurality of resilient support members asymmetrically located about
the axis and extending between the device and the circuit board.
2. (Original) The system of Claim 1, wherein the plurality of resilient
support members are in a compressed state.
3. (Original) The system of Claim 1, wherein the plurality of resilient
support members are configured to engage the circuit board prior to engagement of
the second connector portion with the first connector portion.
4. (Original) The system of Claim 1, wherein one of the first connector
portion and the second connector portion includes a plurality of sockets and wherein
the other of the first connector portion and the second connector portion includes a
plurality of pins received within the plurality of sockets.
5. (Original) The system of Claim 1, wherein the first electronic device
comprises an integrated circuit chip.
6. (Original) The system of Claim 5 including a first heat sink thermally
coupled to the integrated circuit chip.

7. (Original) The system of Claim 6 including a power pod electrically connected to the integrated circuit chip and extending on one side of the second connector portion.

8. (Original) The system of Claim 7 including a second heat sink thermally coupled to the power pod.

9. (Original) The system of Claim 7, wherein the plurality of support members extend between the power pod and the circuit board.

10. (Original) The system of Claim 7, wherein at least a portion of the power pod extends between at least one of the plurality of support members and the second connector portion.

11. (Original) The system of Claim 1 including a plurality of guide members symmetrically located about the axis.

12. (Original) The system of Claim 11, wherein the plurality of guide members comprises four guide members.

13. (Original) The system of Claim 1, wherein the plurality of support members includes at least one spring.

14. (Original) The system of Claim 1, wherein the plurality of support members includes at least one resilient foam member.

15. (Original) A computing component comprising:
a first electronic device;
a first connector portion electrically connected to the first device and configured to be electrically connected to a second connector portion coupled to a circuit board along a first axis; and
a first resilient support member coupled to the electronic device and extending beyond the first connector portion so as to resiliently engage the circuit board or a structure coupled to the circuit board prior to the first connector portion being connected to the second connector portion.

16. (Original) The component of Claim 15 including:
a second resilient support member coupled to the electronic device and extending beyond the first connector portion so as to resiliently engage the circuit board or the structure coupled to the circuit board prior to the first connector portion being connected to the second connector portion.
17. (Original) The component of Claim 16, wherein the first resilient support member and the second resilient support member are asymmetrically positioned relative to the first axis.
18. (Original) The component of Claim 15, wherein one of the first connector portion and the second connector portion includes a plurality of sockets and wherein the other of the first connector portion and the second connector portion includes a plurality of pins received within the plurality of sockets.
19. (Original) The component of Claim 15, wherein the first electronic device comprises an integrated circuit chip.
20. (Original) The component of Claim 19 including a first heat sink thermally coupled to the integrated circuit chip.
21. (Currently Amended) The component of Claim 20 including a power pod electrically connected to the integrated circuit chip and coupled to the integrated circuit chip as a unit while extending on one side of the second connector portion.
22. (Original) The component of Claim 21 including a second heat sink thermally coupled to the power pod.
23. (Original) The component of Claim 15 including a plurality of guide members symmetrically located about the axis.
24. (Original) The component of Claim 23, wherein the plurality of guide members comprises four guide members.

25. (Original) The component of Claim 15, wherein the plurality of support members includes at least one spring.

26. (Original) The component of Claim 15, wherein the plurality of support members includes at least one resilient foam member.

27. (Original) The component of Claim 15, wherein the component has a first longitudinal end and a second opposite longitudinal end, wherein the first connector portion has a longitudinal center spaced from the first end by a first distance and wherein the first resilient support member is located between the first connector portion and the second end and is spaced from the longitudinal center of the first connector portion by a second distance greater than the first distance.

28. (Original) A processor component comprising:
a processor device;
a first connector portion electrically connected to the processor device and configured to be connected to a second connector portion connected to a circuit board;
a power pod electrically connected to the processor device so as to supply power to the processor device;
at least one heat sink thermally coupled to the processor device and the power pod; and
a first resilient support member extending beyond the first connector portion and configured to be compressed during connection of the first connector portion to the second connector portion, wherein at least a portion of the power pod extends between the first support member and the first connector portion.

29. (Original) The processor component of Claim 28 including a second resilient support member extending beyond the first connector portion and configured to be compressed during connection of the first connector portion to the second connector portion, wherein at least a portion of the power pod extends between the second support member and the first connector portion.

30. (Original) The processor component of Claim 29, wherein the first resilient support member and the second resilient support member are asymmetrically positioned relative to the first connector portion.

31. (Original) A computing system comprising:
a circuit board;
a first connector portion electrically connected to the circuit board; and
an electronic component having a first end and a second opposite end,
the electronic component including:
an electronic device;
a second connector portion electrically connected to the
electronic device and electrically connected to the first connector portion along a first
axis; and
means for resiliently supporting the second end relative to the
circuit board as the first connector portion is being connected to the second
connector portion.

32. (Original) A method for connecting an electronic component having a
first end, an opposite second end, an electronic device, and a first connector portion
closer to the first end than the second end, to a circuit board having a second
connector portion, the method comprising:
substantially aligning the first connector portion with the second
connector portion; and
resiliently supporting the second end as the first connector portion is
moved into interconnection with the second connector portion.

33. (Original) A computing system comprising:
a circuit board;
a first connector portion electrically connected to the circuit board;
an electronic component having a center of mass and including:
an electronic device; and
a second connector portion electrically connected to the
electronic device and configured to be coupled to the first connector portion along a

connection axis offset from the center of mass, whereby the electronic component experiences a first torque about a tilt axis perpendicular to and intersecting the connection axis; and

an offset compensation system including:

at least one force applying mechanism coupled to one of the circuit board and the electronic component and configured to apply force to the other of the circuit board and the electronic component at at least one location such that a second opposite torque about the tilt axis is exerted to the electronic component prior to connection of the first connector portion and the second connector portion.

34. (Original) The system of Claim 33, wherein the second opposite torque is substantially equal to the first torque in magnitude.

35. (Original) The system of Claim 33, wherein the center of mass of the electronic component extends between the connection axis and the at least one location at which force is applied.

36. (Original) The system of Claim 33, wherein the at least one force applying mechanism includes at least one spring.

37. (Original) The system of Claim 33, wherein the at least one force applying mechanism includes at least one resilient foam material.

38. (Cancelled)

39. (Original) The system of Claim 38, wherein the at least one force applying mechanism includes a resilient member resiliently supporting the force applying member.

40. (Original) A computing system comprising:
a circuit board;
a first connector portion electrically connected to the circuit board;
an electronic component having a center of mass and including:
an electronic device; and
a second connector portion electrically connected to the electronic device and configured to be coupled to the first connector portion along a connection axis offset from the center of mass, whereby the electronic component experiences a first torque about a tilt axis perpendicular to and intersecting the connection axis; and
an offset compensation system including:
means for applying to the electronic component a second torque about the tilt axis opposite to the first torque prior to connection of the first connector portion and the second connector portion.

41. (Original) The system of Claim 40, wherein the second torque is substantially equal to the first torque in magnitude.

42. (Original) An offset compensation system for use with an electronic component having a first connector portion connected to a second connector portion associated with a circuit board, wherein the electronic component has a center of mass offset from a connection axis along which the first connector portion and the second connector portion connect such that the electronic component experiences a first torque about a tilt axis perpendicular to and intersecting the connection axis, the offset compensation system including:

at least one force applying mechanism configured to be coupled to one of the circuit board and the electronic component and configured to apply force to the other of the circuit board and the electronic component at at least one location such that a second opposite torque about the tilt axis is exerted to the electronic component prior to connection of the first connector portion and the second connector portion.

43. (New) The system of Claim 1, wherein the plurality of resilient support members are carried by the electronic component.

44. (New) The component of Claim 15, wherein the first resilient support member is carried by the electronic component.

45. (New) The component of Claim 28, wherein the first resilient support member is carried by the component prior to the first connector portion being connected to the second connector portion.